

IN THE CLAIMS:

Please amend the claims as follows:

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16. (Once Amended) An IC chip package as defined in Claim 1, wherein the grease has a weight loss at about 100°C after 30 days of less than about 0.15%.

93 17. (Once Amended) An integrated circuit (IC) chip package with IC chip elements having an IC chip with an active surface, the active surface having extending therefrom an electrical connector in electrical communication with the IC chip, the IC chip being mounted upon a substrate, the IC chip package comprising:

a grease in contact with the active surface of the IC chip; and

a container disposed upon the substrate and enclosing a volume external to the IC chip elements, wherein the grease is enclosed within the container and the substrate, and wherein the grease fills the volume enclosed by the container.

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a4 41. (Once Amended) An IC chip package with IC chip elements having an IC chip with an active surface, the active surface having an electrical connector extending therefrom in electrical communication with the IC chip, the IC chip being mounted upon a substrate, the IC chip package comprising:

a grease in contact with the active surface of the IC chip, the grease having:

a thermal conductivity in a range from about 2 Watts/m·K to about 5 Watts/m·K;

a dielectric constant in a range from less than about 6 to about 9;

and

a melting point in a range from about 190°C to about 220°C; and

a container disposed upon the substrate, the container enclosing a volume external to the IC chip elements, wherein the grease is enclosed within the container and the substrate, and the grease fills the volume enclosed by the container.

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